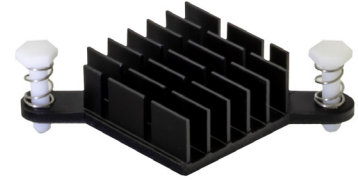




MODEL: HSB39-252509P | **DESCRIPTION:** HEAT SINK

FEATURES

- BGA design
- push pins
- aluminum alloy
- black anodized finish



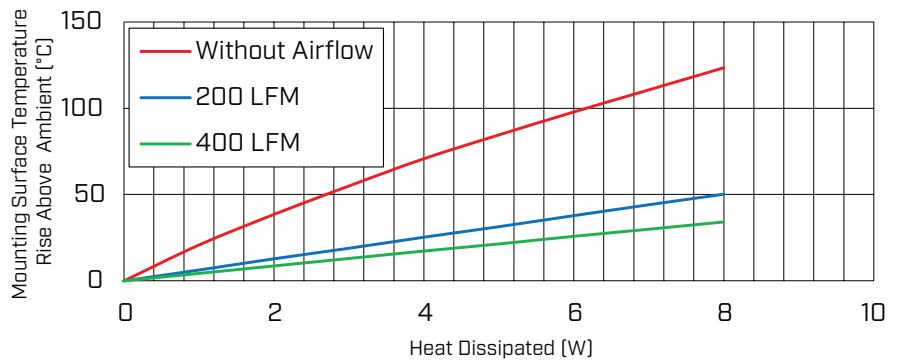
MODEL

	thermal resistance ¹				power dissipation ¹ @ 75°C ΔT, nat conv [W]
	@ 75°C ΔT, nat conv [°C/W]	@ 1 W, nat conv [°C/W]	@ 1 W, 200 LFM [°C/W]	@ 1 W, 400 LFM [°C/W]	
HSB39-252509P	17.53	20.8	6.3	4.3	4.28

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

Power (W)	Heatsink Temperature Rise Above Ambient (ΔT = T _{hs} - T _a) [°C]		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	20.8	6.3	4.3
2	38.5	12.8	8.6
3	55.0	18.9	12.9
4	70.8	25.3	17.2
5	84.6	31.4	21.3
6	97.9	37.8	25.7
7	110.7	44.1	29.8
8	123.5	50.2	34.0

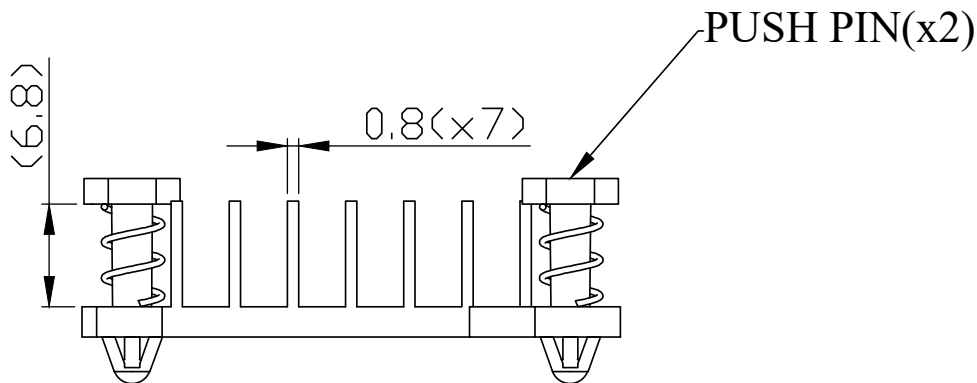
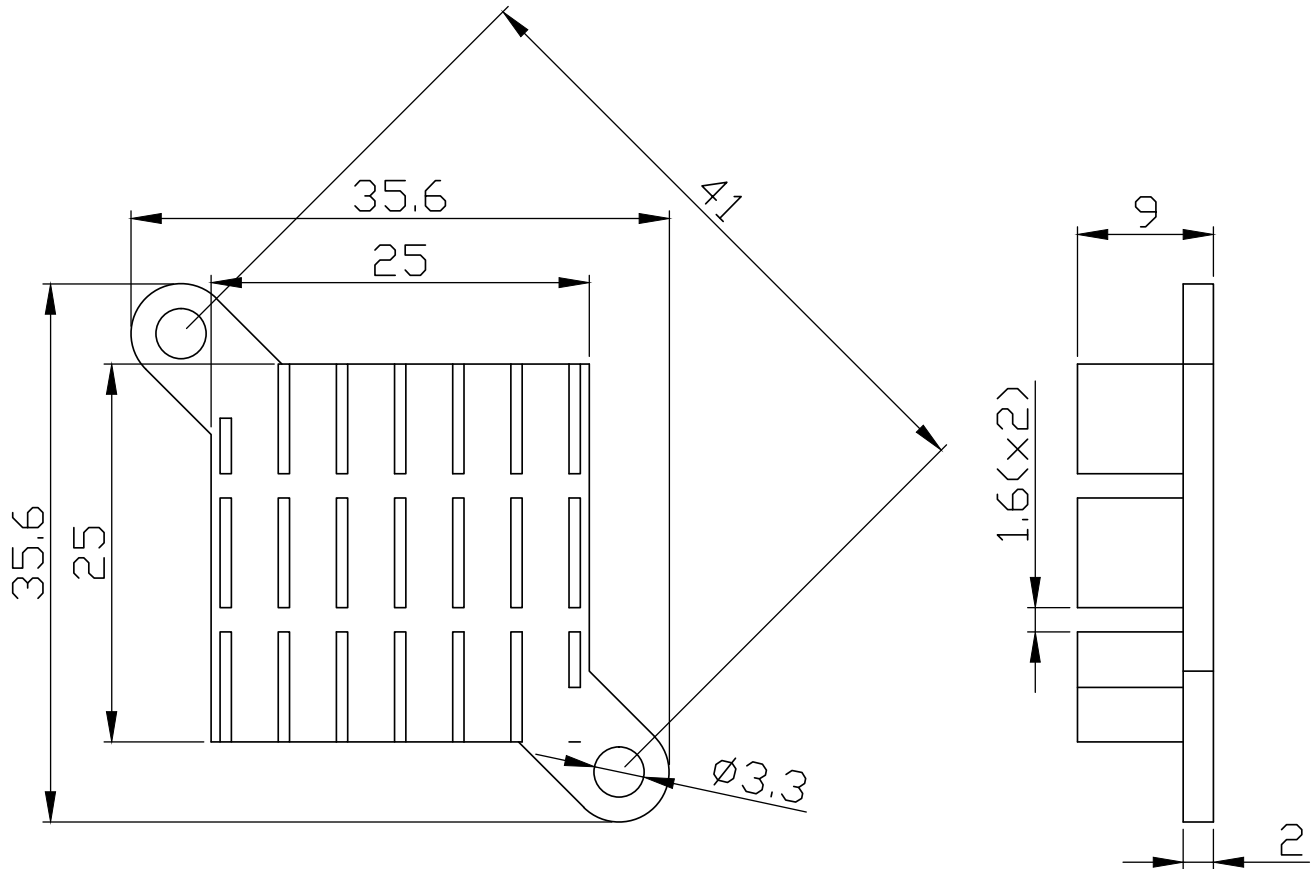


T_{hs}: "hot spot" temperature measured on the heatsink
 T_a: ambient temperature

MECHANICAL DRAWING

units: mm
tolerance: ±0.50 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
PUSH PIN	nylon 66
SPRING	spring steel, zinc plated
WEIGHT	8 g



REVISION HISTORY

rev.	description	date
1.0	initial release	03/01/2024

The revision history provided is for informational purposes only and is believed to be accurate.



CUI Devices offers a one (1) year limited warranty. Complete warranty information is listed on our website.

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